

2008 Solar Annual Review Meeting

Measurements & Characterization (M&C) Capabilities Overview

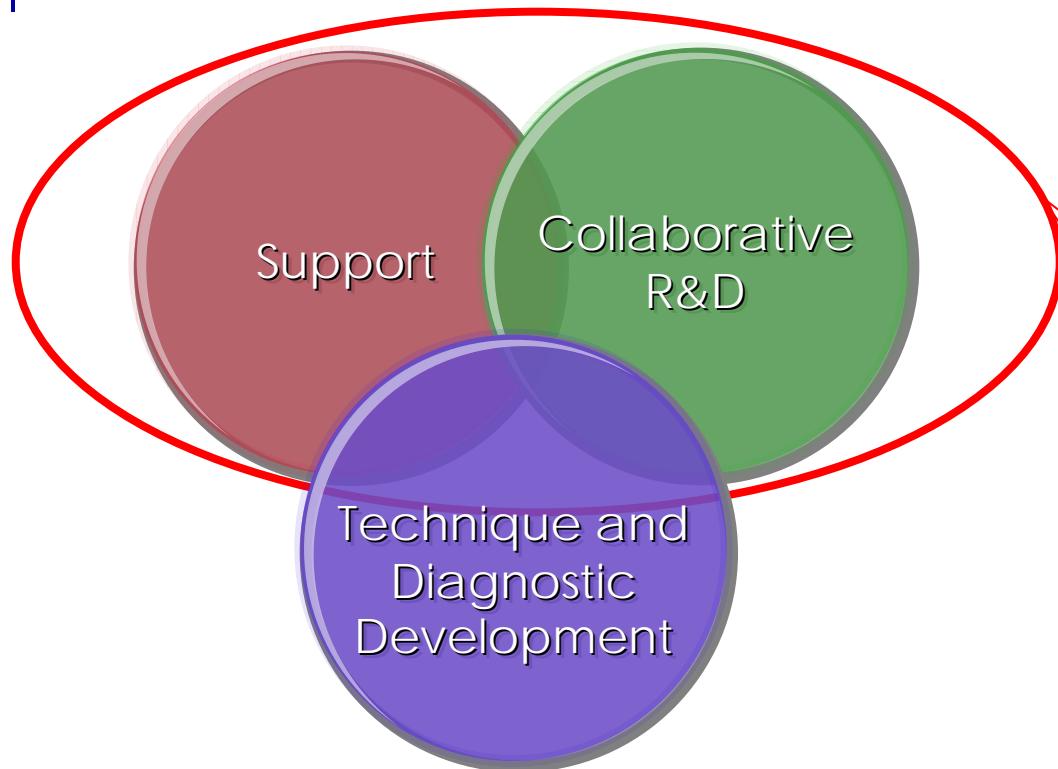


Peter Sheldon
Measurements and Characterization
NREL
1617 Cole Blvd.
Golden, CO 80401



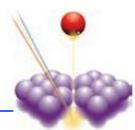


M&C Mission: Three Focus Areas

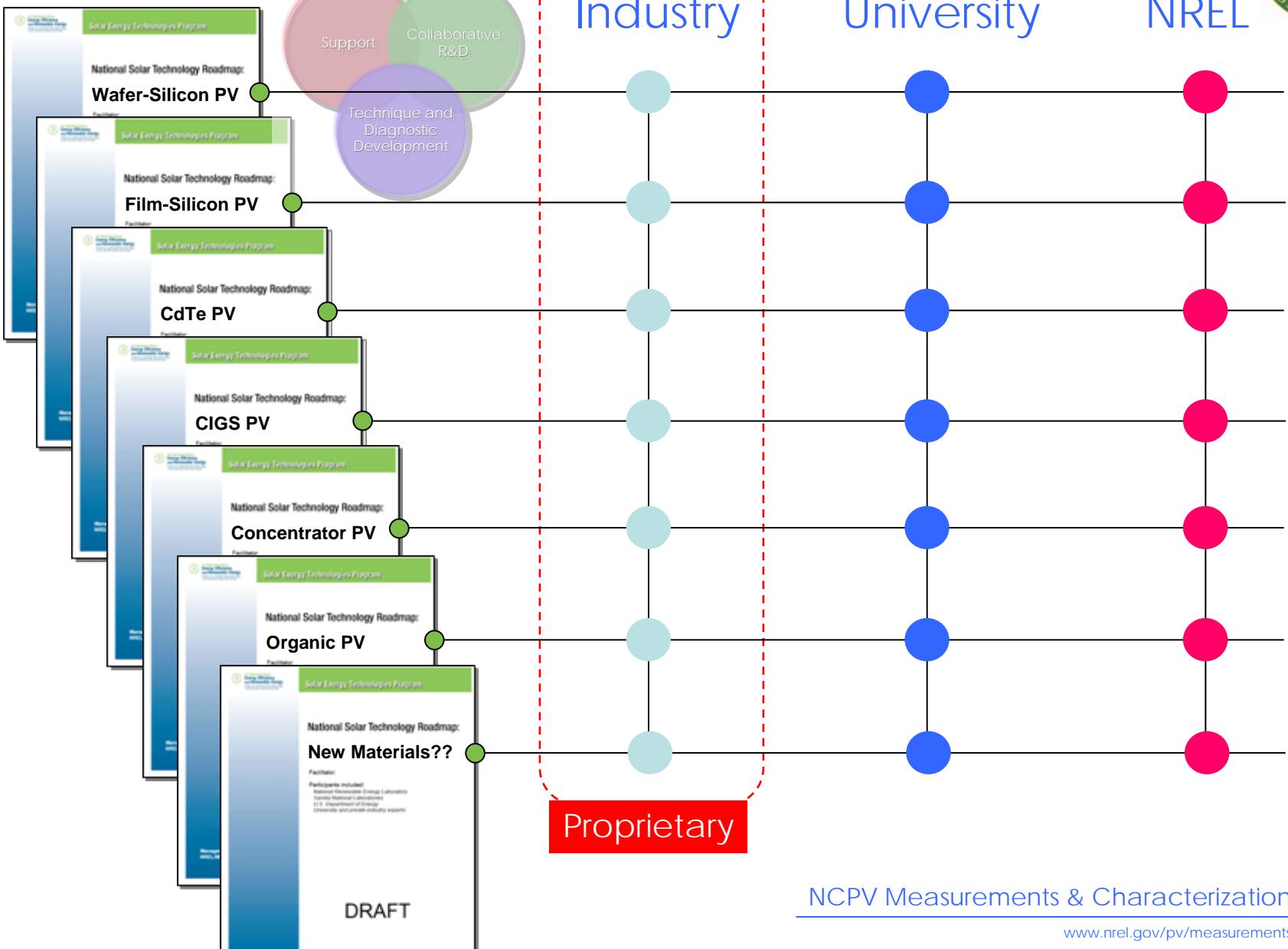


A key component of our mission is to work with SAI subcontractors and help them realize their goals

- Subcontract Stage-gate Review
- Test & Evaluation
- Process Development and Device R&D
- Cell/Module Failure Analysis R&D



M&C Collaborations



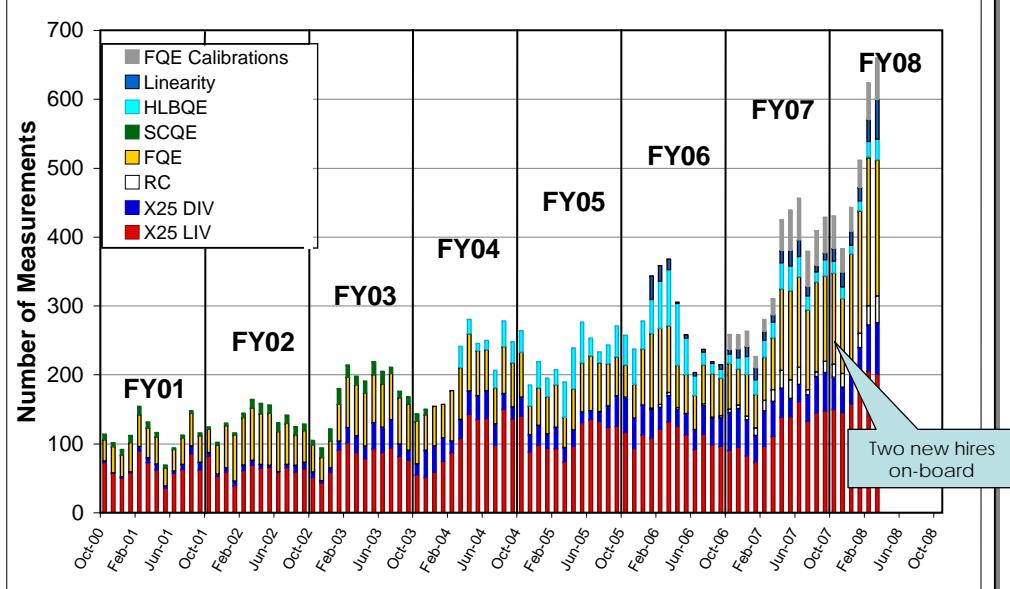


M&C Supported Subcontracts

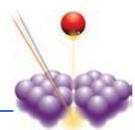
2008 Subcontractor Funding:

Photovoltaic Systems R&D Technology Pathway Partnerships (TPPs)	~\$51M
PV Technology Incubator	~18M
University Photovoltaic Product and Process Development	~\$4M
<u>Next Generation Photovoltaic Devices and Processes</u>	~\$7M
TOTAL	~\$80M

Cell Lab Measurements versus Test Bed



- Top priority/preferential treatment for SAI deliverables and stage gate reviews
- Support for all DOE-funded subcontracts on a first come first serve basis (no differentiation between TPP, Incubator, and pre-SAI subcontracts)
- Non-SAI funded PV industry requests





M&C Core Competency Areas

National Center
for Photovoltaics (NCPV)

Measurements &
Characterization

Peter Sheldon
peter_sheldon@nrel.gov



Device
Performance

Keith Emery
keith_emery@nrel.gov



Electro-Optical
Characterization

Dean Levi
dean_levi@nrel.gov



Surface
Analysis

Sally Asher
sally_asher@nrel.gov



Analytical
Microscopy

Mowafak Al-Jassim
mowafak_aljassim@nrel.gov



M&C Core Competency Areas

National Center
for Photovoltaics (NCPV)

Measurements &
Characterization

Peter Sheldon
peter_sheldon@nrel.gov



Device
Performance

Keith Emery
keith_emery@nrel.gov



Electro-Optical
Characterization



Surface
Analysis



Analytical
Microscopy

Cell and Module Performance Team

- *Independent facility for verifying device and module performance for the entire PV community*
- *ISO 17025 accredited for primary reference cell, secondary reference cell and secondary module calibrations*
- *Provide the U.S. PV industry with a calibration traceability path for peak-watt and efficiency measurements to reduce uncertainty in I-V measurements*
 - *Provide reference cell calibrations for the entire US terrestrial community*
- *Develop hardware, software and procedures to accommodate new cell and module technologies. Assists industry in developing measurement system hardware and procedures*



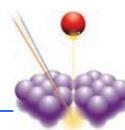
Device Performance



Certificate Number 223601
ISO 17025 accredited for photovoltaic secondary cell, secondary module and primary reference cell calibration by the American Association for Laboratory Accreditation (A2LA)



NCPV Measurements & Characterization



Cell and Module Performance Team Capabilities

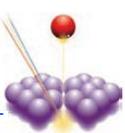


Application	Light Source	Test Bed
1-Sun Cells & Mini-Module		
Spectrolab X25	filtered 3 kW Xe Spectrolab X25 0.1 - 20 suns	30 cm x 30 cm
Concentrator Cells		
Continuous Illumination	1 kW Xenon or 3kW Tungsten 0.1 - 200 suns	1 cm diameter for Xe 5 cm x 10 cm for W
High Intensity Pulsed Solar Simulator (HIPSS)	Xe Flash Lamp 1 to 2000 suns	2 cm x 20 cm
Modules		
Spire 240A Solar Simulator	Xe flash lamp 0.1 to 1.2 suns	61 cm x 122 cm
Spire 4600 Solar Simulator <i>On Order</i>	Pulsed Light Source	137 cm x 200 cm
Spectrolab X200 Large-area Continuous Solar Simulator (LACSS)	Filtered 25 kW Xe 0.1 to 1 suns	122 cm x 152 cm
Standard Outdoor Measurement System (SOMS)	Sunlight	200 cm x 300 cm

Outdoor Test Facility Expansion Project



- 2,300 gsf of new and reconfigured space
- Required to accommodate large-area solar simulator necessary to support the SAI
- A new Spire 4600 simulator will allow test of modules up to 137 cm x 200 cm (a 265% increase in size)



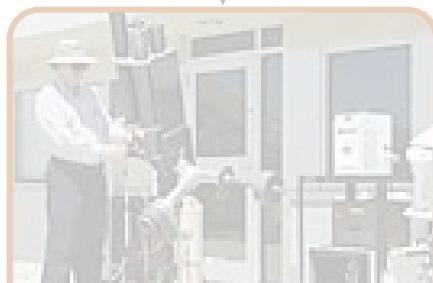


M&C Core Competency Areas

National Center
for Photovoltaics (NCPV)

Measurements &
Characterization

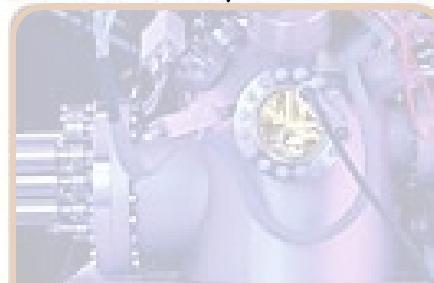
Peter Sheldon
peter_sheldon@nrel.gov



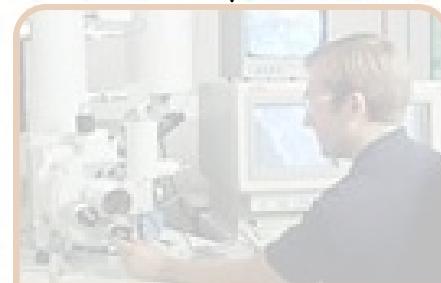
Device
Performance



Electro-Optical
Characterization



Surface
Analysis



Analytical
Microscopy

Dean Levi
dean_levi@nrel.gov

Electro-Optical Characterization Team

Capabilities

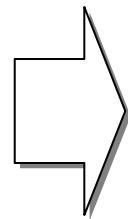
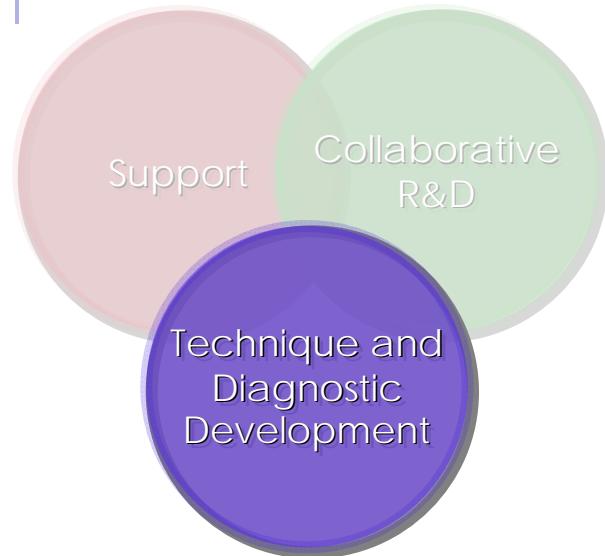


Electro-Optical
Characterization

<i>Technique/Capability</i>	<i>Typical Applications</i>
Photoluminescence Spectroscopy	<i>Measure bandgap and alloy composition; identify defects; provides a quick measure of material quality</i>
Minority Carrier Lifetime <i>TRPL, RC-PCD, and μW-PCD</i>	<i>Measure minority-carrier lifetime, material quality, surface/interface recombination and surface passivation; identify dominant recombination mechanisms</i>
Fourier Transform Infrared Spectroscopy	<i>Identify chemical composition, chemical bonding; analyze in-situ reactions and concentration of impurities; measure inhomogeneity</i>
Spectroscopic Ellipsometry <i>VASE and RTSE</i>	<i>Determine optical constants; layer thicknesses; surface/interface roughness; as well as composition crystallinity, alloy composition, and growth dynamics of films</i>
Capacitance Techniques <i>C-V, DLTS, AS, and DLCP</i>	<i>Measure carrier concentration profiles, interface state densities, and deep-level properties</i>
Computational Modeling	<i>2-D solar cell modeling and simulation of measurement techniques (TRPL, RC-PCD, EBIC, QE, IV, CL, C-AFM)</i>
Diagnostic Development	<i>PVSCAN, PV Reflectometer, RC-PCD, PLI, and CDI</i>

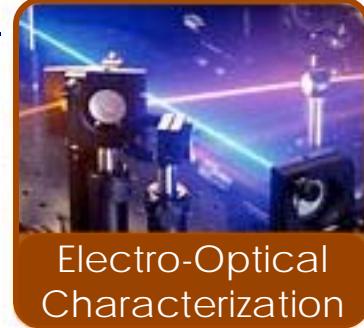


Electro-Optical Diagnostic Development



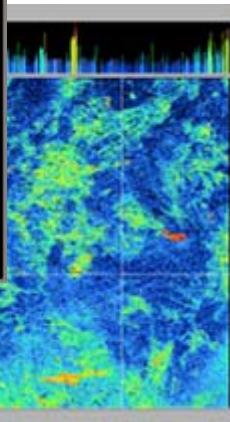
NREL Developed Diagnostics:

- **PV Scan** Licensed
- **PV Reflectometer** Licensed
- **RC-PCD** In- Process



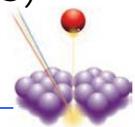
GT-PVSCAN 8000

- High-speed optical scanning system designed for characterization of PV materials and cells
 - Technology developed at NREL and licensed to GT Solar
 - 8' x 8" sample size
 - Measurement Modes:
 - Dislocation density
 - Reflectance
 - Light Beam Induced Current (LBIC)



NCPV Measurements & Characterization

www.nrel.gov/pv/measurements



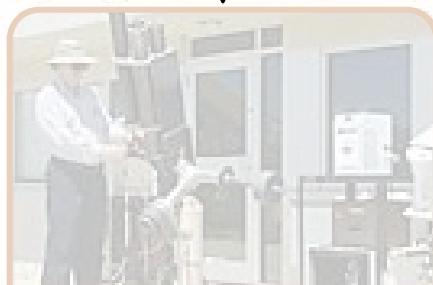


M&C Core Competency Areas

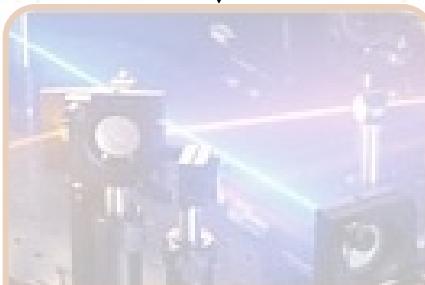
National Center
for Photovoltaics (NCPV)

Measurements &
Characterization

Peter Sheldon
peter_sheldon@nrel.gov



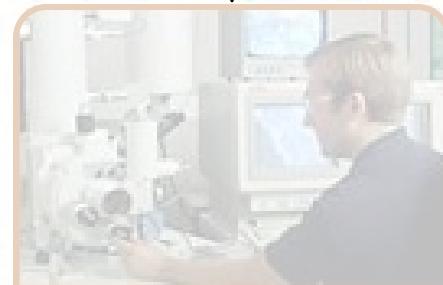
Device
Performance



Electro-Optical
Characterization



Surface
Analysis



Analytical
Microscopy

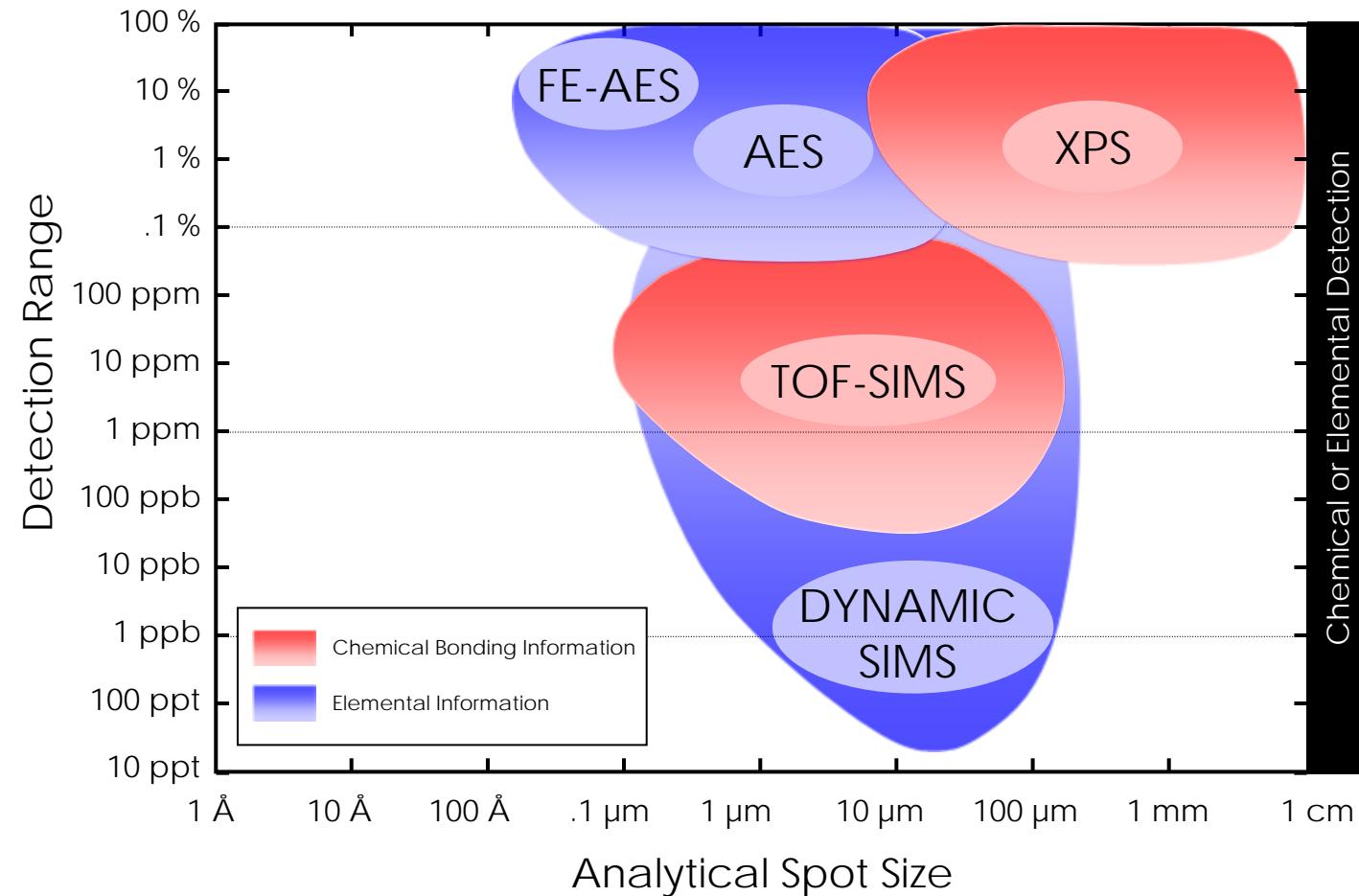
Sally Asher
sally_asher@nrel.gov

Surface Analysis Team Capabilities



Surface Analysis

Analytical Resolution versus Sensitivity



AES

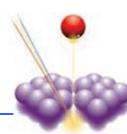
Auger Electron Spectroscopy

- Elemental information
- Detects Li - U
- 0-100Å depth resolution
- Depth profiling capable
- Imaging capability

XPS

X-ray Photoelectron Spectroscopy

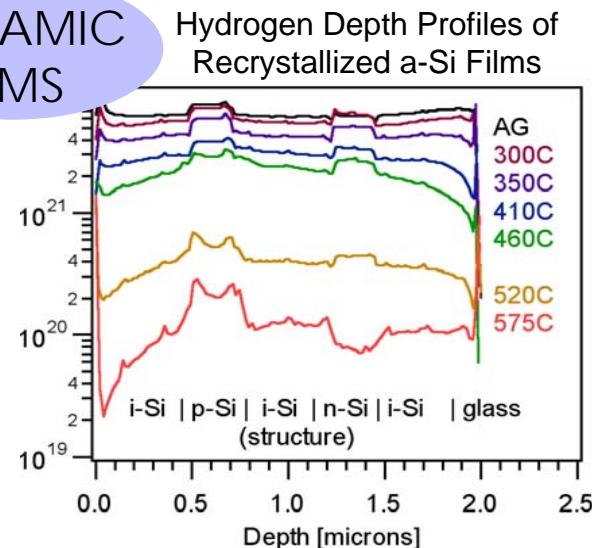
- Chemical Bonding Info.
- Detects Li - U
- 0-100Å depth resolution
- Depth profiling capable
- Imaging capability



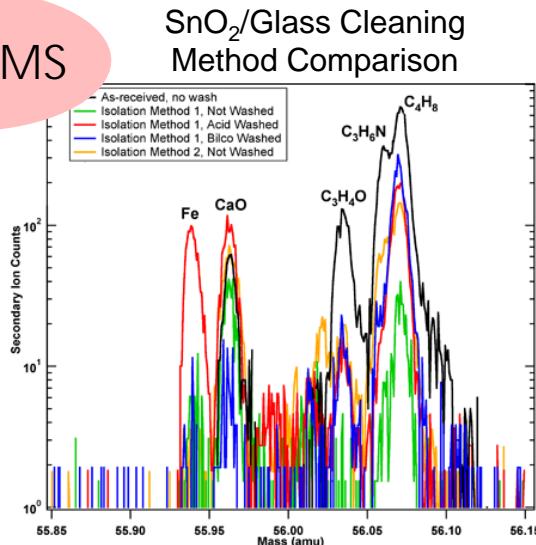
Secondary Ion Mass Spectrometry (SIMS)

Time-of-Flight SIMS (TOF-SIMS)

DYNAMIC SIMS



TOF-SIMS



Surface Analysis

- Extremely sensitive - Detects fractions in the range of parts per million (ppm) to parts per billion (ppb)
- Elemental detection of species ranging from H to U and all isotopes
- Quantitative technique when used with standards
- Depth profiles with resolution of <10 nm - Excellent technique for analyzing interfaces

- Extremely sensitive - Detects fractions in the parts per million (ppm) range
- Elemental and molecular analysis- good for analyzing organics
- Surface sensitive technique - can study the top few monolayers of material
- Elemental detection of species ranging from H to U and all isotopes
- Depth profiles with resolution of <5 nm

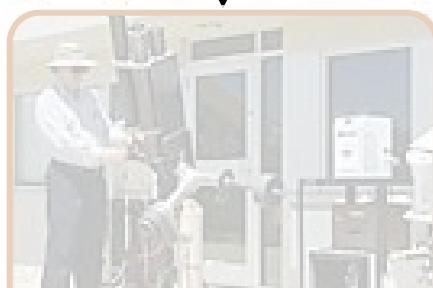


M&C Core Competency Areas

National Center
for Photovoltaics (NCPV)

Measurements &
Characterization

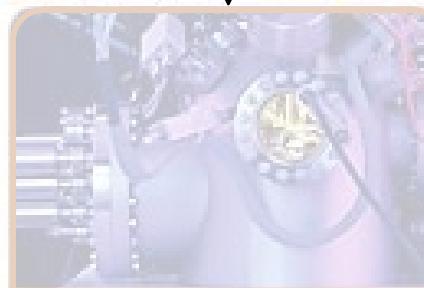
Peter Sheldon
peter_sheldon@nrel.gov



Device
Performance



Electro-Optical
Characterization



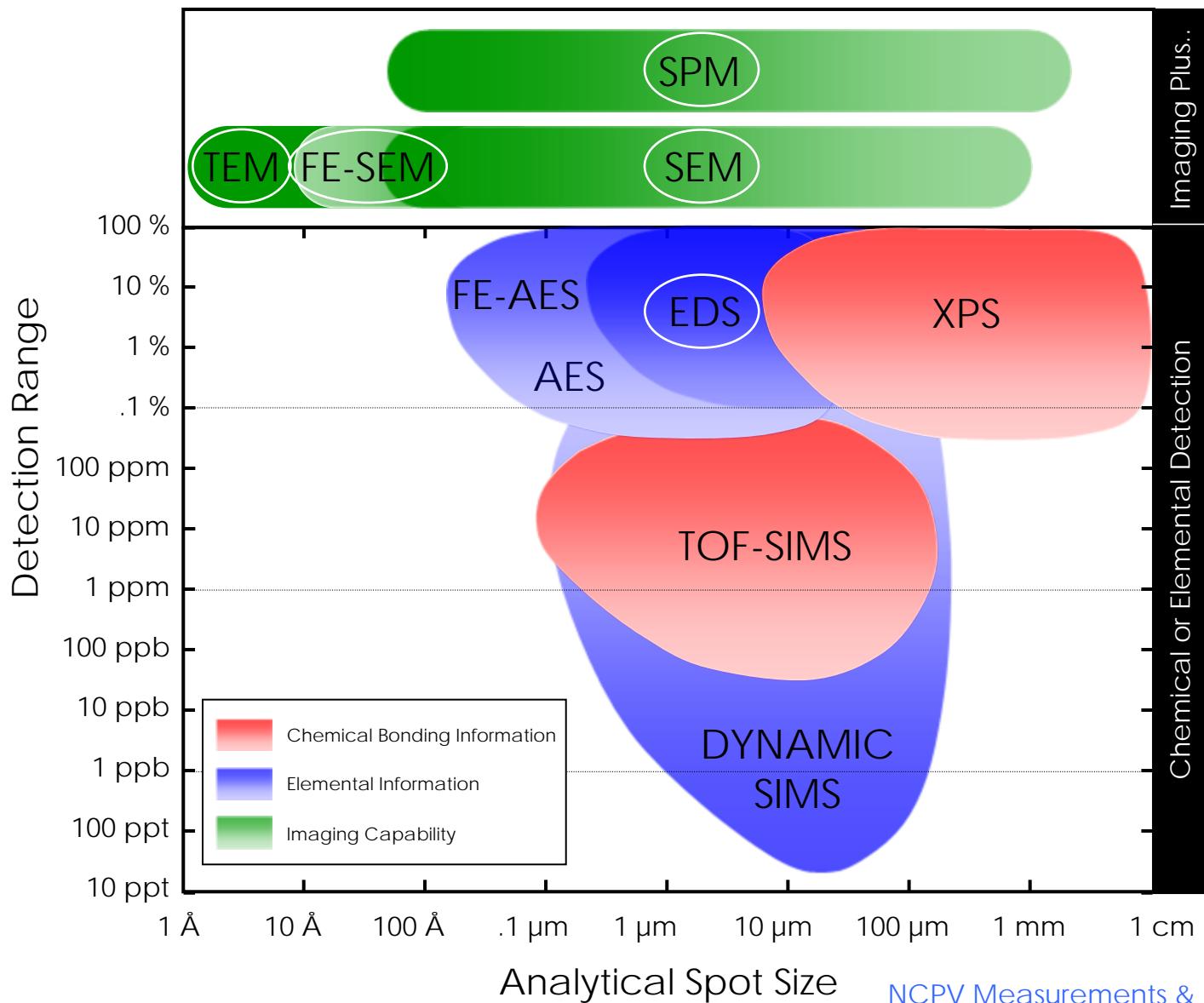
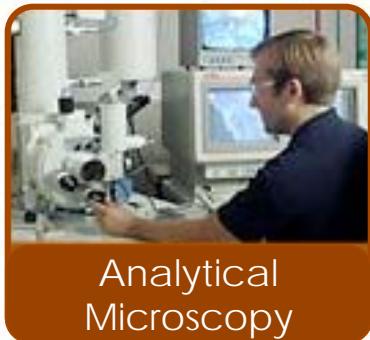
Surface
Analysis



Analytical
Microscopy

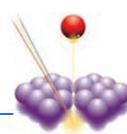
Mowafak Al-Jassim
mowafak_aljassim@nrel.gov

Analytical Microscopy Team Capabilities

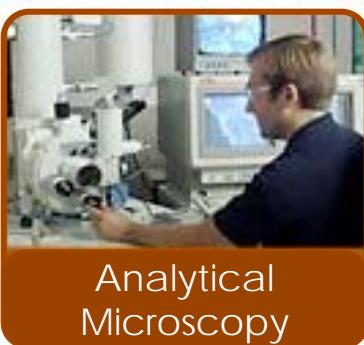


NCPV Measurements & Characterization

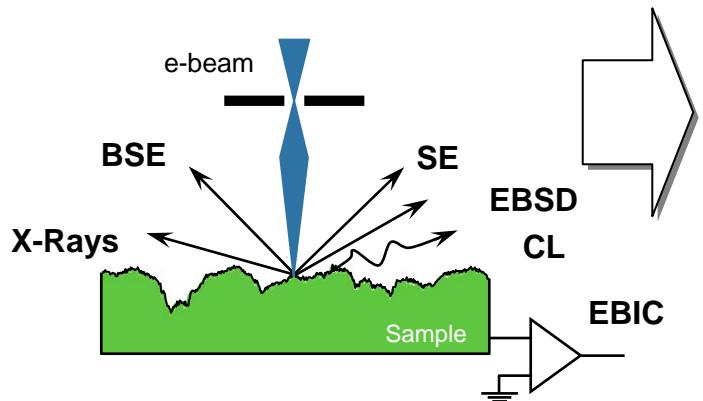
www.nrel.gov/pv/measurements



SEM and SPM Capabilities

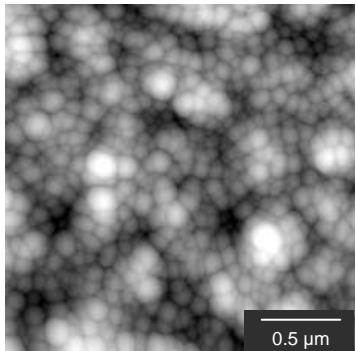


SEM Operational Modes



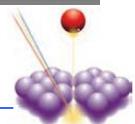
- Secondary Electron (SE) Imaging
- Back Scattered Electron (BSE) Imaging
- Cathodoluminescence (CL)
- Electron beam induced current (EBIC)
- Electron backscattered diffraction (EBSD)
- Energy dispersive x-ray spectroscopy (EDS)

SPM Operational Modes

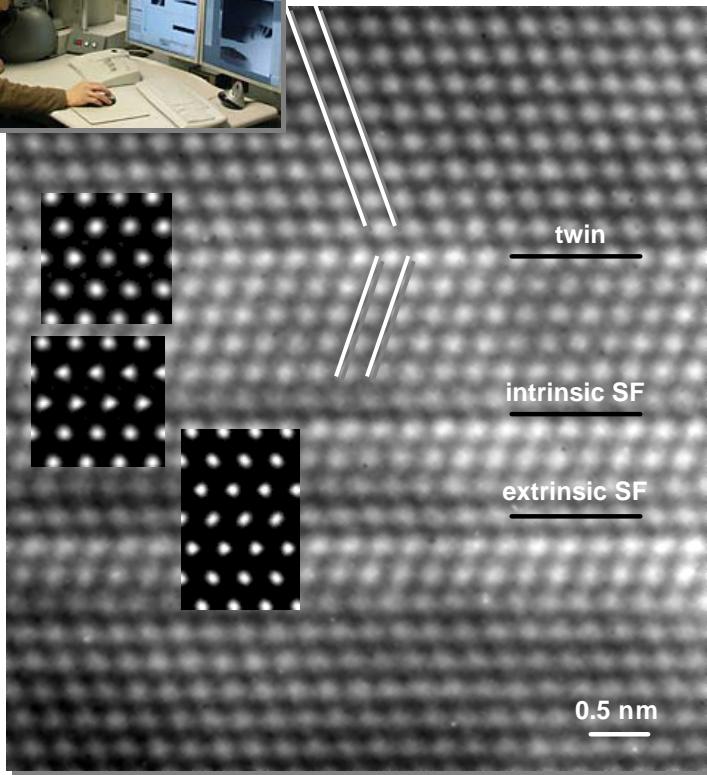


SEM-based

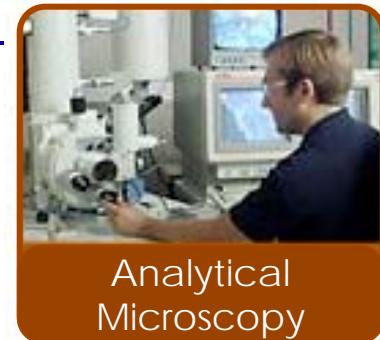
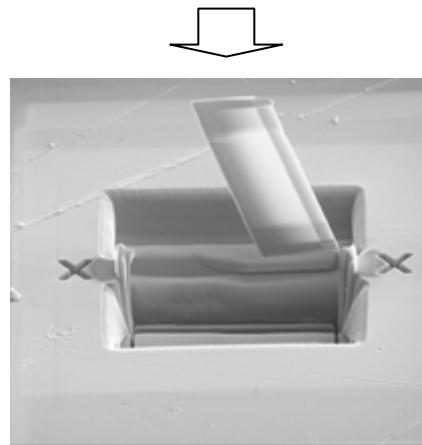
- Atomic Force Microscopy (AFM)
 - Conductive AFM (C-AFM)
 - Scanning Capacitance Microscopy (SCM)
 - Scanning Kelvin Probe Microscopy (SKPM)
-
- Scanning Tunneling Luminescence (STL)
 - Electroluminescence (EL) Mapping
 - Near-field cathodoluminescence (NFCL)



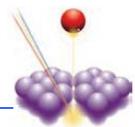
Transmission Electron Microscopy (TEM)



- **High-Resolution Imaging** -
Atomic resolution (1.4 \AA)
- **Structural Analysis** -
Electron diffraction and diffraction contrast analysis
- **Compositional Analysis** - Energy dispersive spectroscopy (B to U , $\sim 0.5 \text{ at\%}$)
- **Cross-Sectional Analysis** - New Focused Ion Beam (FIB) capability facilitates cross-sectional sample prep with pin-point accuracy.



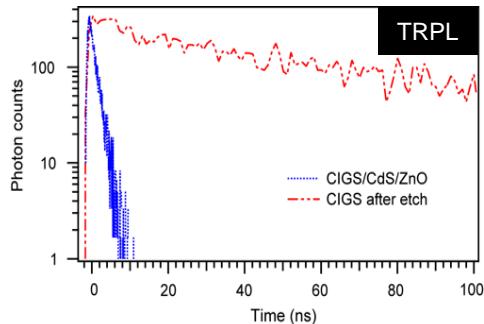
Analytical
Microscopy





Combining Complementary Techniques

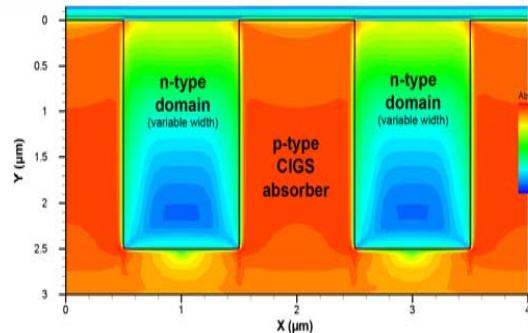
E-O Characterization



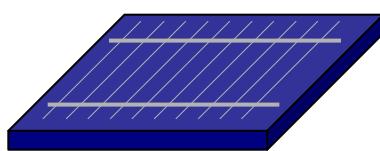
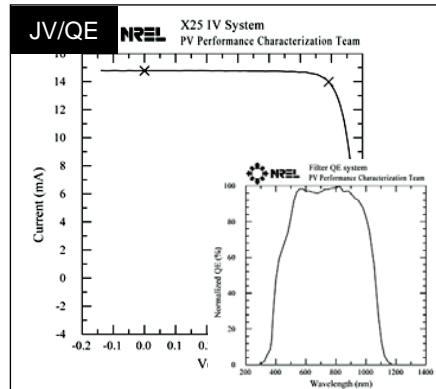
Process Knowledge



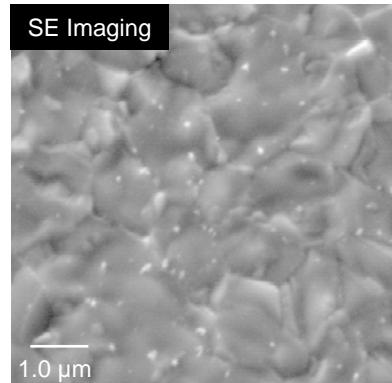
Device Modeling



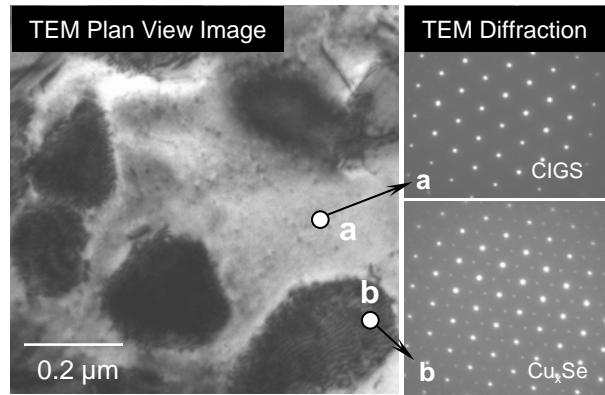
Device Performance



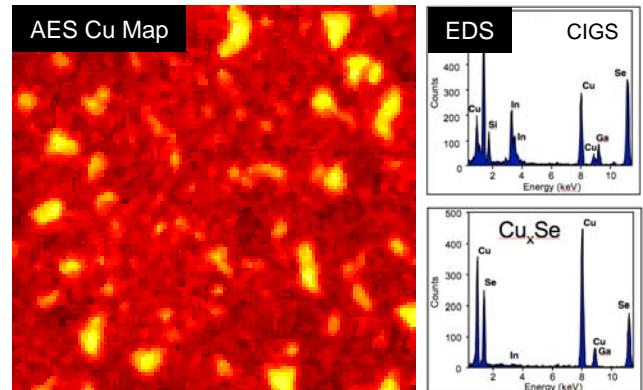
Topography



Structural Characterization



Compositional Characterization





M&C Capabilities

National Renewable Energy Laboratory
Innovation for Our Energy Future

Measurements & Characterization • National Center for Photovoltaics
SURFACE ANALYSIS

Surface analytical techniques help determine the chemical, elemental, and molecular composition, and electronic properties of material surfaces and interfaces. The properties of the surface and outer few micrometers of a material control the electrical, chemical, or mechanical properties of that material—hence, the range of its ultimate importance.

This fact is important to us because, at NREL, we focus on the physical, chemical, and electrical composition of surfaces and interfaces. We map the elemental and chemical composition of surfaces, study impurities at grain boundaries, gather bonding and chemical-state information, measure surface electronic properties, and perform depth profiles to determine the physical properties of materials. We have analysts in a wide range of disciplines, including physicochemical analysis, atomic force microscopy, scanning photoluminescence, and optical and thermal properties.

We work collaboratively with you to solve materials- and device-related R&D problems. This sheet describes our major facilities and capabilities.

FIELD EMISSION AUGER ELECTRON SPECTROSCOPY (FE-AES)
With atomic resolution, FE-AES can analyze materials in contact with a focused beam of high-energy (~1–10 keV) electrons. This is ideal for lossless energy-loss mapping, because it generates Auger signals that have specific energy-loss characteristics of the writing atom.

This technique provides useful data during the automated composition mapping of Auger electrons from a limited escape depth. A key capability of the FE-AES is its ability to scan the electron beam to a small spot, with resolutions similar to an electron microscope. By scanning the beam across the surface, we generate both element-specific Auger maps and secondary-electron micrographs (SEM) images from the same region of the sample.

MAJOR INSTRUMENTATION FOR SURFACE ANALYSIS

Analyzed Material	Instrumentation Type	Typical Applications	Working Distance	Open Beam	Signal Type	Elemental Depth	Other Depth
Auger electron spectroscopy FE-AES	Scanning electron microscope, with electron beam	Elemental composition analysis, semi- quantitative surface analysis	25 nm	Auger electrons	UHV	1–5 nm	10–50 nm
X-ray and ultraviolet photoelectron spectroscopy XPS/UWPS	Chamber based photoelectron spectrometer, ultraviolet photoelectron spectrometer	Elemental composition analysis, surface electronic properties	50 nm	Photoemitted electrons	UHV/U	1–2 nm	10–50 nm
Scanning tunneling microscopy STM	Scanning tunneling microscope	Elemental composition analysis, surface electronic properties	1 nm	STM current	1–2 nm	10–50 nm	10–50 nm
Static TOF-SIMS	TOF-SIMS and SIMS	Surface element analysis, molecular imaging	1 nm	1 nm	TOF-SIMS current	<1 nm	10–50 nm

National Renewable Energy Laboratory
Innovation for Our Energy Future

Measurements & Characterization • National Center for Photovoltaics
ELECTRO-OPTICAL CHARACTERIZATION

We use various optical and pit-of-experiment techniques to relate photo voltaic device performance to the methods and materials used to produce them. The type of information obtained by these techniques is often unique to the device under investigation. For large-scale electro-optical characterization, such as optical methods and electron-stimulated properties, accurate, timely measurements of electro-optical properties as a function of device processing provide the knowledge needed to develop and validate models. This knowledge has a reducing cost, maximizing efficiency, improving reliability, and enhancing device durability. We work collaboratively with you to solve materials- and device-related R&D problems. This sheet summarizes our primary techniques and capabilities.

PHOTOLUMINESCENCE SPECTROSCOPY
Photoluminescence (PL) spectroscopy is a technique, based on the excitation of a material, to obtain the electronic structure of materials. Our capability includes various excitation methods that allow for varying levels of volume excitation, such as pulsed lasers, with wavelengths ranging from 0.4 to 2.7 μm; sample temperatures of 4 to 300 K; and mapping capabilities with 1–10-μm spatial resolution on the PL spectra. PL is a non-destructive technique and spectral analysis of the emitted photon fluorescence is a direct measure of various important material properties, including:

- Bandgap determination. This is particularly useful when working with new compound semiconductors.
- Impurity levels and defect detection. The PL energy centroid with its two levels can be used to identify specific defects in the material.
- Recombination mechanism analysis. Analysis of PL helps to understand the underlying physics of the recombination process.

Major areas of application include:

Techniques most
both direct and
time resolution
resolution for PL
and other optical
techniques.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition
and quality of green absorber materials.



NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Surface/Interface
of interest on the
sample**.

NREL researchers are using PL to probe the composition and quality of green absorber materials.

■ **Minority-carrier lifetime** in the p-type
region of the p-n junction in the
device converts inc-
circuit. These opto-
luminescence (OL)
and PL, and

■ **Electron-hole pair
recombination** in the
p-type region of the
device converts inc-
circuit. These opto-
l